

IS66WVQ2M4DALL/BLL
IS67WVQ2M4DALL/BLL

8Mb QUADRAM
1.8V/3.0V SERIAL PSRAM MEMORY WITH 200MHZ QUAD DDR (x4 xSPI INTERFACE) PROTOCOL

DATA SHEET

8Mb QUADRAM

SERIAL PSRAM MEMORY WITH 200MHz QUAD DDR (x4 xSPI) Interface

FEATURES

- **Industry Standard Serial Interface**
  - Quad DDR (x4 xSPI) Interface:
    Command (1 byte) =SDR
    Address (2-byte) & Data = DDR
  - Low Signal Counts :7 Signal pins (CS#, SCLK, DQSM, SIO0~SIO3)

- **High Performance**
  - Double Data Rate (DDR) Operation:
    200MHz (200MB/s) at 1.8V VCC (1)
    133MHz (133MB/s) at 3.0V VCC
  - Source Synchronous Output signal during Read Operation (DQSM)
  - Data Mask during Write Operation (DQSM)
  - Configurable Latency for Read/Write Operation
  - Supports Variable Latency mode and Fixed Latency mode
  - Configurable Drive Strength
  - Supports Wrapped Burst mode and Continuous mode
  - Supports Deep Power Down mode
  - Hidden Refresh

- **Burst Operation**
  - Configurable Wrapped Burst Length : 16, 32, 64, and 128
  - Continuous Operation:
    - Continues Read operation until the end of array address (No Wrapped)
    - Continues Write operation even after the end of array address (Wrapped to first address)

- **Low Power Consumption**
  - Single 1.7V to 1.95V Voltage Supply
  - Single 2.7V to 3.6V Voltage Supply
  - 20 mA Operating at 200MHz (1.8V, max.)

- **Hardware Features**
  - **SCLK Input**: Serial clock input
  - **SIO0 – SIO3**:
    Serial Data Input or Serial Data Output
  - **DQSM**:
    - Output during command, address transactions as Refresh Collision Indicator
    - Output during read data transactions as Read Data Strobe
    - Input during write data transactions as Write Data Mask
  - **RESET#:** Hardware Reset pin

- **Temperature Grades**
  - Industrial: -40°C to +85°C
  - Auto (A2) Grade: -40°C to +105°C
  - Auto (A3) Grade: -40°C to +125°C

- **Industry Standard PACKAGE**
  - B = 24-ball TFBGA 6x8mm 5x5 Array
  - KGD (Call Factory)

GENERAL DESCRIPTION

The IS66/67WVQ2M4DALL/BLL are integrated memory device containing 16Mb Pseudo Static Random Access Memory, using a self-refresh DRAM array organized as 1M words by 8 bits.

The device supports Quad DDR interface, which is compatible with JEDEC standard x4 xSPI Flash.

The device supports Very Low Signal Count (7 signal pins; SCLK, CS#, DQSM, and 4 SIOs), Hidden Refresh Operation, and Automotive temperature (A3, -40°C to +125°C) operation.

Due to DDR operation, minimum transferred data size is a byte (8 bits) through 4 SIO pins.

PERFORMANCE SUMMARY

Read / Write Operation		
Package	VCC	Maximum Clock Rate
24-ball BGA	1.8V	200MHz
	3.0V	133MHz

Maximum Current Consumption		
Burst Read or Write (Continuous Burst at 200MHz, 1.8V)		20 mA
Power On Reset		20 mA
Standby (CS# = High, 125°C)	3V	300 uA
	1.8V	300 uA
Deep Power Down (CS# = High, 125°C)	3V	50 uA
	1.8V	30 uA

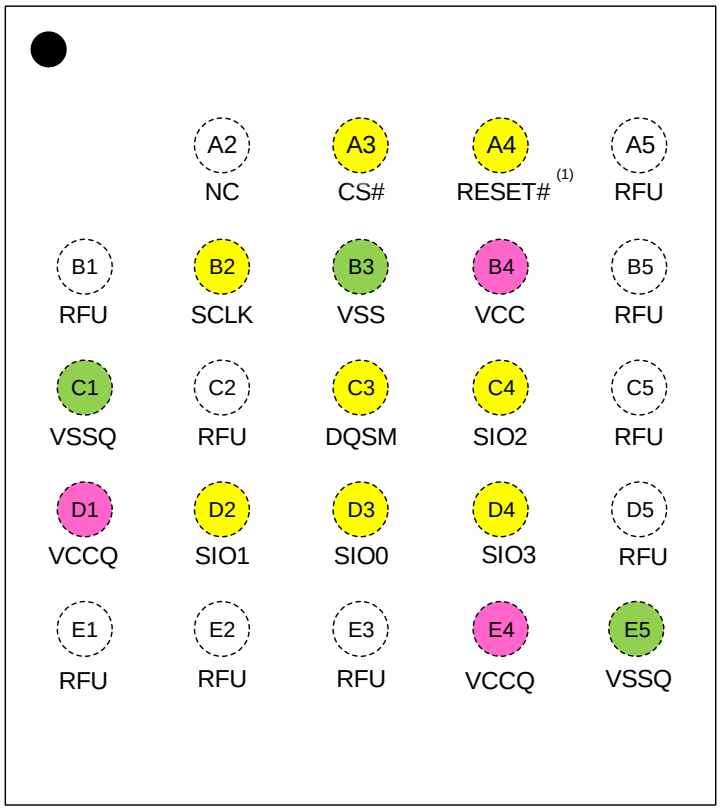
TABLE OF CONTENTS

FEATURES 2
GENERAL DESCRIPTION 3
PERFORMANCE SUMMARY 3
TABLE OF CONTENTS 4
1. PIN CONFIGURATION 5
2. PIN DESCRIPTIONS 6
3. BLOCK DIAGRAM 7
4. COMMAND AND ADDRESS ASSIGNMENTs 8
5. Memory READ/WRITE OPERATIONS 10
5.1 Memory READ OPERATIONS 10
5.2 WRITE OPERATIONS 13
5.3 PREAMBLE BIT Data PATTERN READ OPERATION 16
5.4 RESET OPERATION 17
5.5 POWER-UP INITIALIZATION 18
6. REGISTER 19
6.1 REGISTER READ/WRITE OPERATION 19
6.2 CONFIGURATION REGISTER 20
6.3 DEVICE IDENTIFICATION REGISTER 25
6.4 IN BAND RESET 26
7. ELECTRICAL CHARACTERISTICS 28
7.1 ABSOLUTE MAXIMUM RATINGS (1) 28
7.2 OPERATING RANGE 28
7.3 DC CHARACTERISTICS 29
7.4 PIN CAPACITANCE (TA = 25°C, VCC=1.8V/ 3V, 1MHz) 30
7.5 AC CHARACTERISTICS 31
8. PACKAGE TYPE INFORMATION 35
8.1 24-Ball Thin Profile Fine Pitch BGA 6x8mm 5x5 BALL ARRAY (B) 35
9. ORDERING INFORMATION – Valid Part Numbers 36

1. PIN CONFIGURATION

24-ball TFBGA (5x5 ball array)

Top View, Balls Facing Down



Note:

1. **RESET# pin can be left floating when not used.**

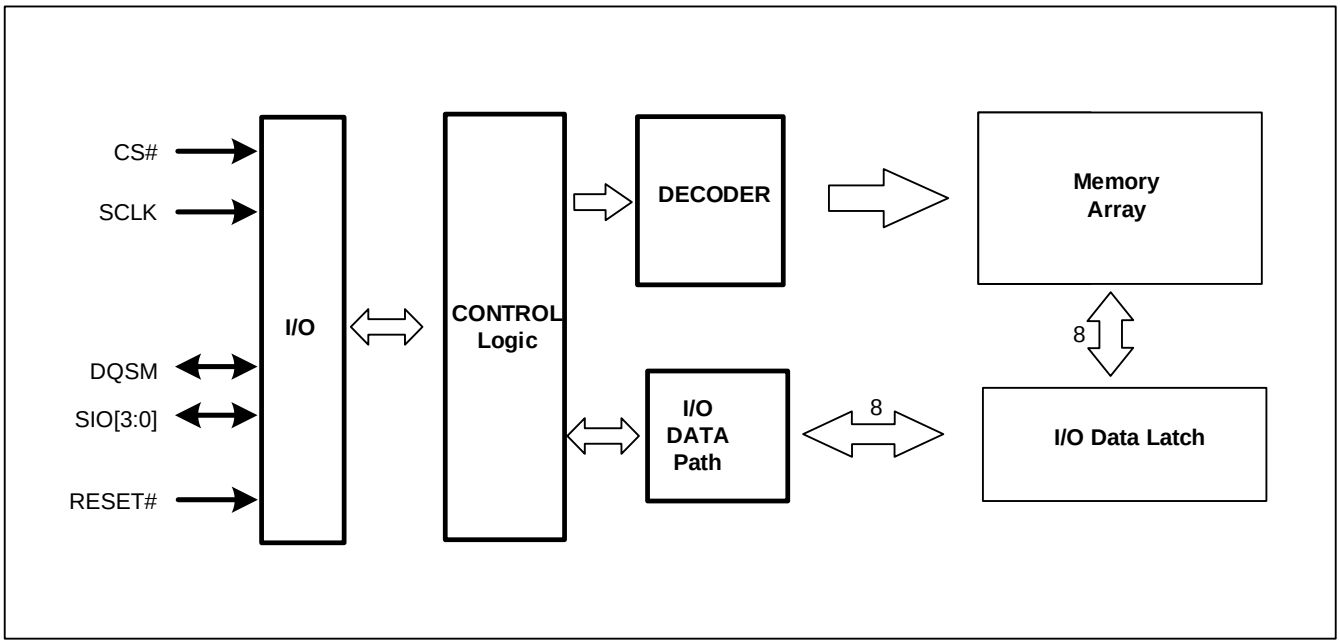
2. PIN DESCRIPTIONS

SYMBOL	TYPE	DESCRIPTION
CS#	INPUT	**Chip Select:**
DQSM	INPUT/OUTPUT	**Refresh Collision Indicator [2], Data Strobe Signal in Read operation, and Write Data Mask in Write operation:**
RESET#[1]	INPUT	**RESET#:** The RESET# pin is a hardware RESET signal. When RESET# is driven High, the memory is in the normal operating mode. When RESET# is driven Low, the memory enters reset mode and output is High-Z.
SIO0-SIO3	INPUT	**Serial Data Input & Output pins**.
SCLK	INPUT	**Serial Data Clock:** Synchronized Clock for input and output timing operations.
VCC	POWER	**Power Supply**
VCCQ	POWER	**IO Power Supply**
VSS	GROUND	**Ground**
VSSQ	GROUND	**IO Ground**
RFU	Reserved	**RFU:** Reserved for future use: May or may not be connected internally.

Notes:

1. RESET# pin has an internal pull-up.
2. Contact ISSI MKT for DQSM without Refresh Collision Indicator

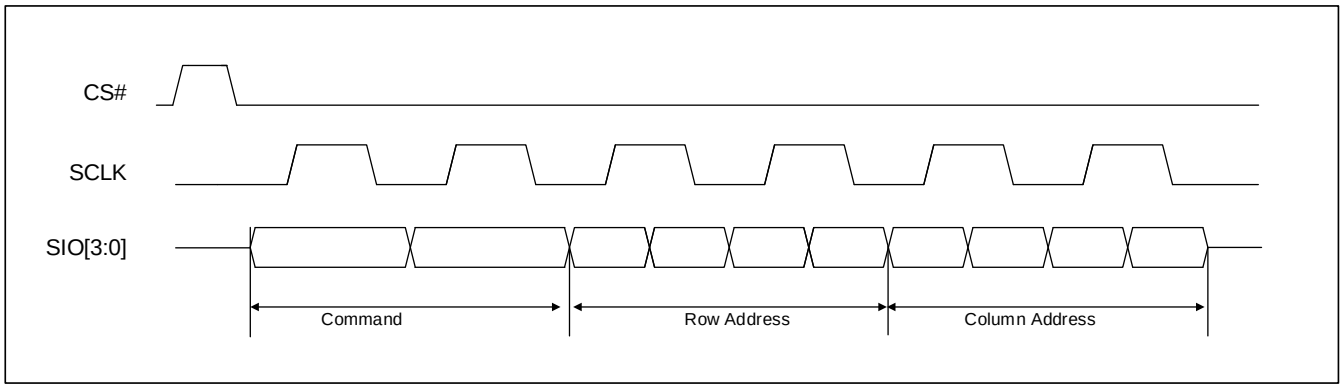
3. BLOCK DIAGRAM



4. COMMAND AND ADDRESS ASSIGNMENTs

The device is serial interface, so all command and address inputs are transferred through SIO pins.

Figure 4.1 Command and Address Cycles



Notes:
1. The figure shows the initial six clock cycles of input operations.
2. Command and Address information is "center aligned" with the clock during both Read and Write operations.

Table 4.1 Command / Address bit assignment

Clock	1st clock	2nd clock	3rd clock		4th clock		5th clock		6th clock	
Function	**Command (8-bit)**		**Row address**				**Column address**			
SIO[3]	Command		Reserved	RA11	RA7	RA3	Reserved	CA6	CA2	Reserved
SIO[2]			Reserved	RA10	RA6	RA2	Reserved	CA5	CA1	Reserved
SIO[1]			Reserved	RA9	RA5	RA1	Reserved	CA4	CA0	Reserved
SIO[0]			RA12	RA8	RA4	RA0	Reserved	CA3	Reserved	Reserved

Notes:

1. The 16Mb QUADRAM address assignments:
   - Row Address 12 ~ 0: 8K (13 bits), Column Address 6 ~ 0: 128 (7 bits), 8Mb density = 8K X 128 (bytes)
2. Data is always transferred in full byte increment (byte granularity -8 bits-transfer).

Table 4.2 Command / Address bit assignment

Command	Clock 1, 2		Clock 3, 4		Clock 5, 6	
	Command (SDR)		Row address (DDR)		Column address (DDR)	
Memory READ with continuous burst	Ah	0h	RA[12:0]		CA[6:0]	
Memory READ with wrapped burst	8h	0h	RA[12:0]		CA[6:0]	
Memory WRITE with continuous burst	2h	0h	RA[12:0]		CA[6:0]	
Memory WRITE with wrapped burst	0h	0h	RA[12:0]		CA[6:0]	
Identification Register (read only)	Ch or Eh	0h	00h	00h	00h	00h
Configuration Register READ	Ch or Eh	0h	00h	04h	00h	00h
Configuration Register WRITE	6h	0h	00h	04h	00h	00h
ECC Register READ	Ch or Eh	0h	00h	04h	00h	**03h**
ECC Register WRITE	6h	0h	00h	04h	00h	**03h**
Preamble Bit Pattern READ	Fh	0h	Don't care		CA[6:1] Don't care CA[0] Pattern Selection	

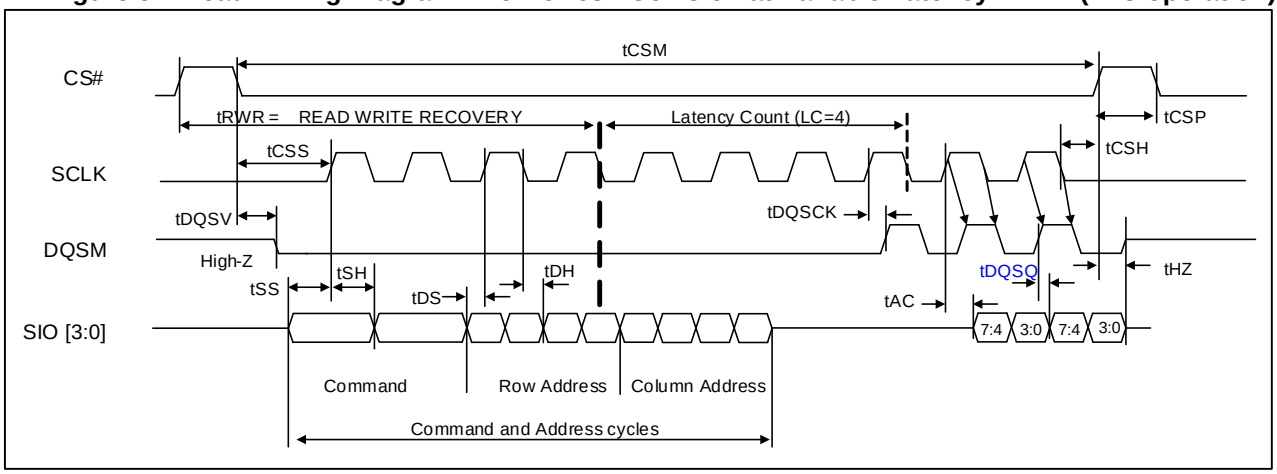
Note:

1. CA[6:0] in 8Mb density:

5. Memory READ/WRITE OPERATIONS

5.1 MEMORY READ OPERATIONS

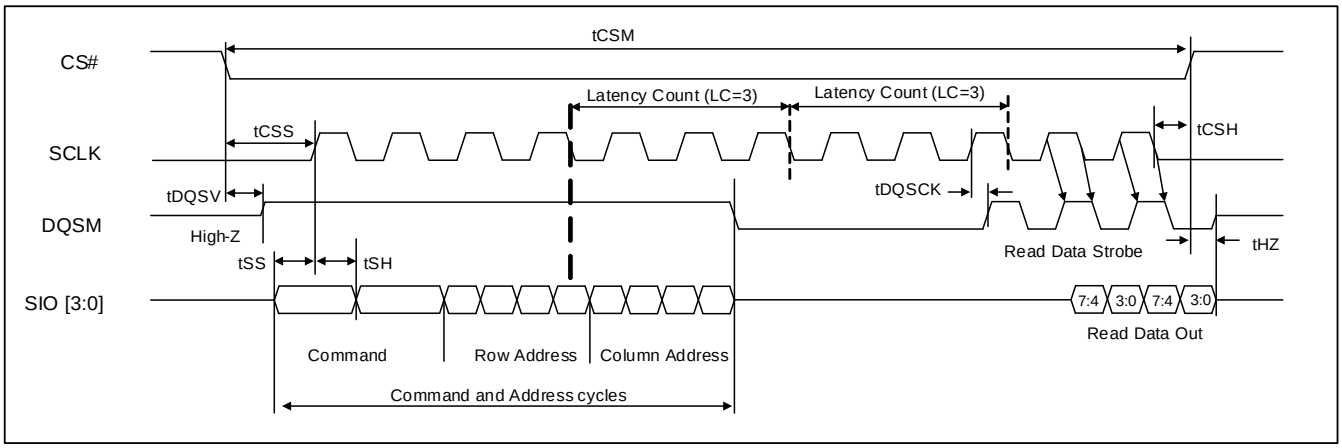
Figure 5.1 Read Timing Diagram - No Refresh Collision at Variable Latency READ (1LC operation)



Notes:

1. The Latency count is defined by the initial latency value in a configuration register.
2. Latency count (LC) is 4 clocks, CR [8] =1 (DQSM 1 clock pre-cycle before Valid READ Data).
3. Diagram in the figure above is representative of **variable latency with no refresh collision access.**
4. Read access (LC) starts once RA [3:0] (falling edge of 4th clock) is captured.
5. The memory drives DQSM during read cycles.
6. DQSM is a read data strobe with data values edge aligned with the transitions of DQSM driven by the device.

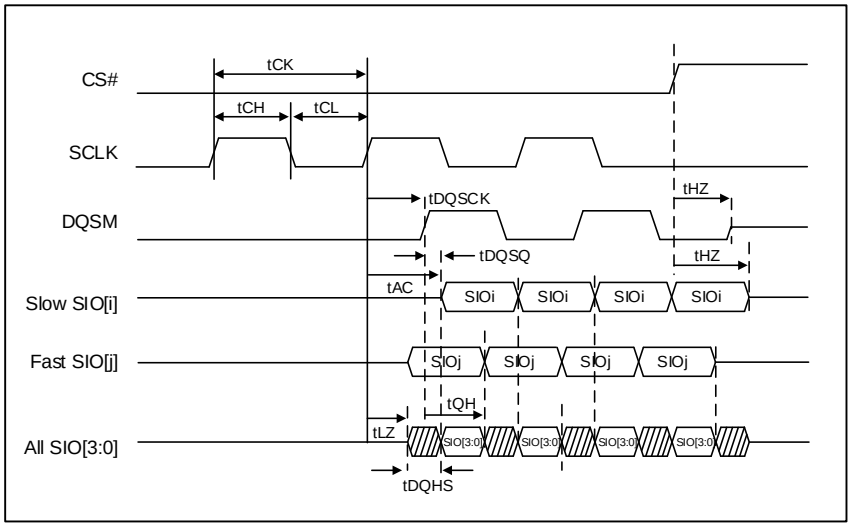
Figure 5.2 Read Timing Diagram - Refresh Collision at Variable-Latency READ (2LC operation)



Notes:

1. The Latency count is defined by the initial latency value in a configuration register.
2. Latency count (LC) is 3 clocks, CR [8] =1 (DQSM 1 clock pre-cycle before Valid READ Data).
3. Diagram in the figure above is representative of **variable latency with refresh collision or fixed-latency access** (2LC operation).
4. In this Read there is a 2 Latency Count (2LC) for read access.
5. Read access (LC) starts once RA [3:0] is captured.
6. The memory drives DQSM during read cycles.
7. DQSM is a read data strobe with data values edge aligned with the transitions of DQSM driven by the device.
8. **Fixed initial READ access latency outputs the first data at a consistent time regardless of worst-case refresh collisions.**

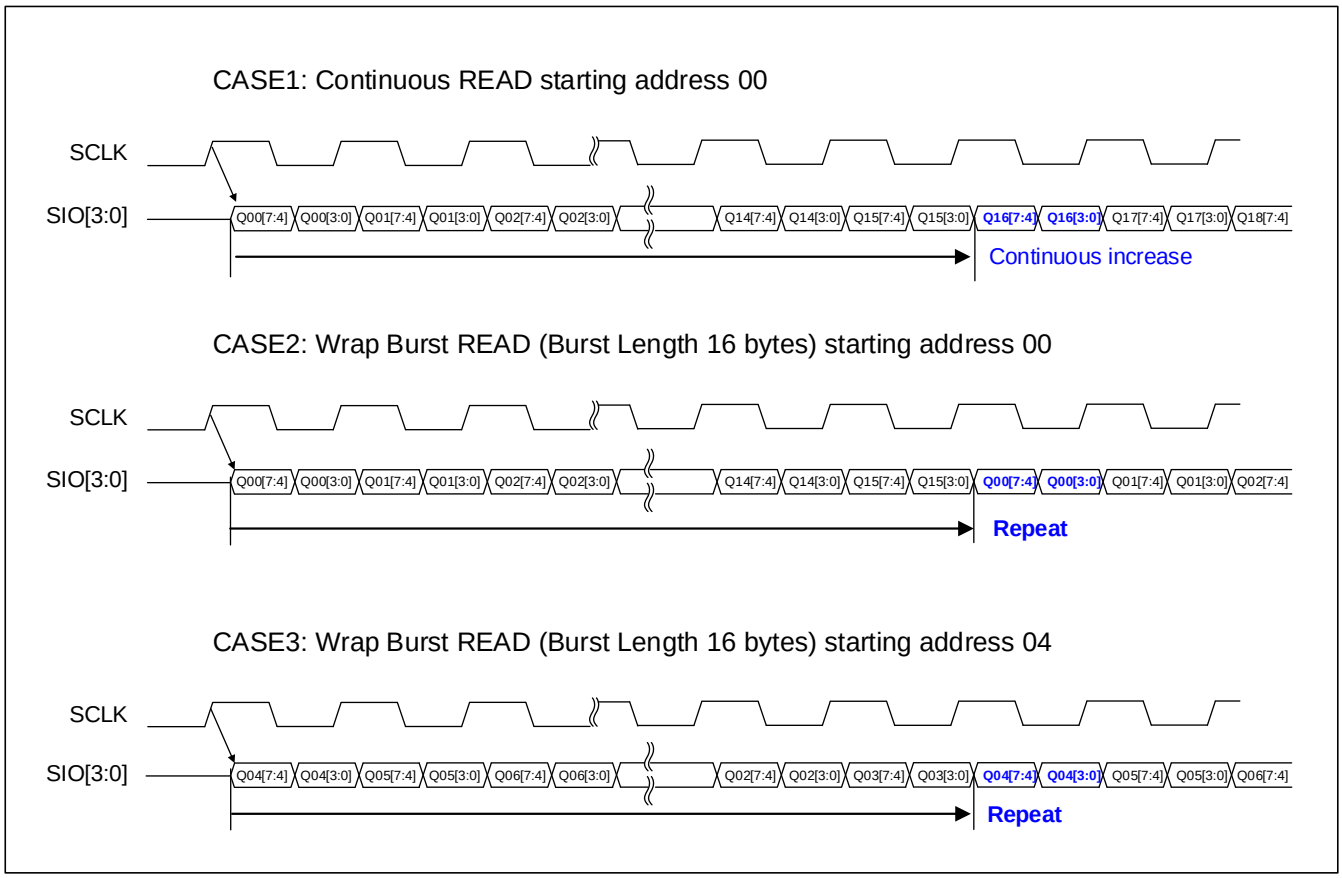
Figure 5.3 Data Valid Timing



Notes:

1. Burst READ data valid timing in detail.
2. tAC defines CLK transition to DQ Valid.
3. tDQSCK defines CLK transition to DQSM Valid.
4. tDQSQ defines DQSM-DQ skew.
5. tQHS defines Data Hold skew factor.
6. tQH defines DQ hold time from DQSM.

Figure 5.4 READ Burst Wrap

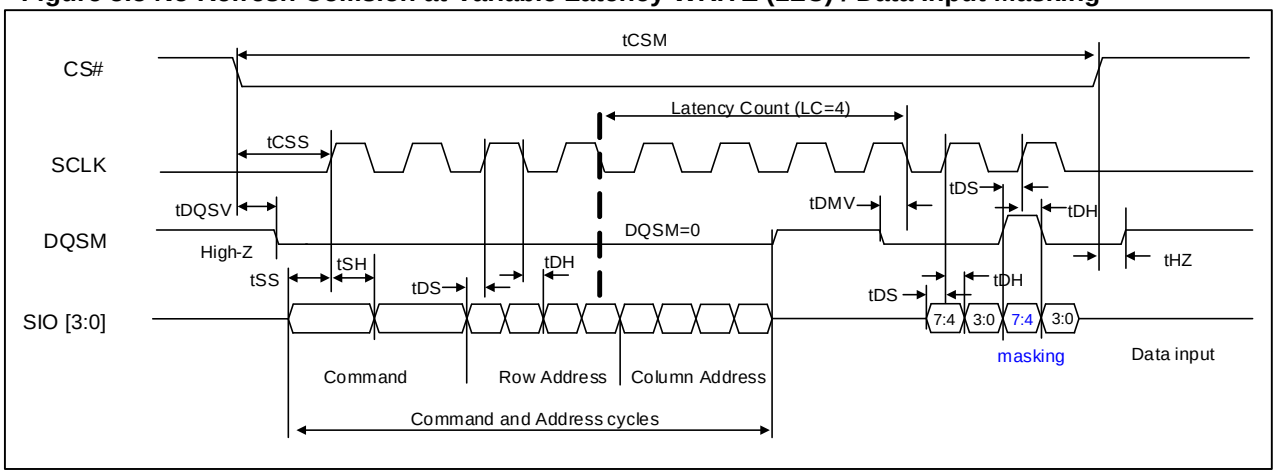


Notes:

1. CS# can stay Low between burst operations, but CS# must not remain Low longer than tCSM.
2. Read operation can be ended at any time by bringing CS# High.
3. Continues Read operation until last address. Continuing beyond last address, undefined data will be available.

5.2 WRITE OPERATIONS

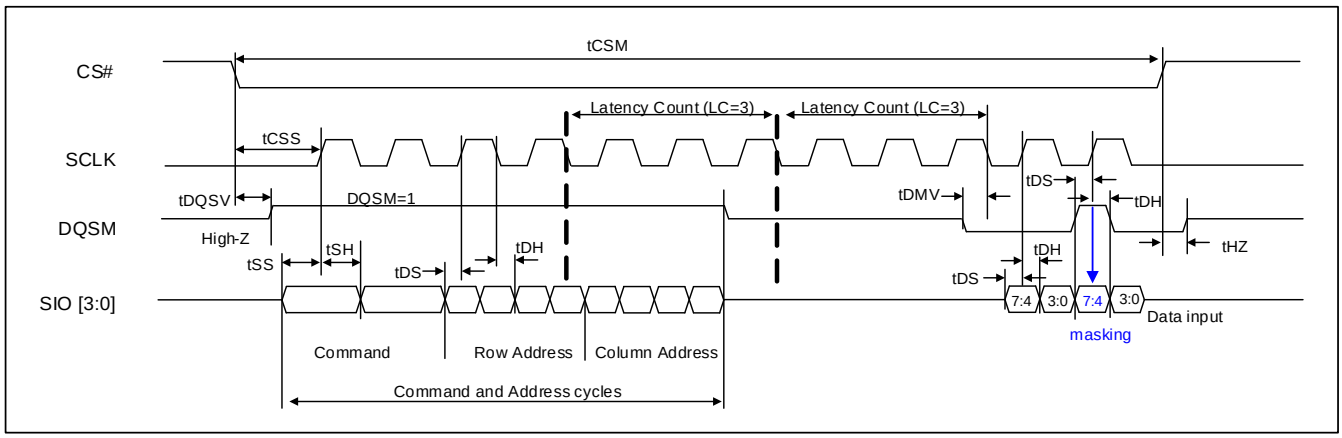
Figure 5.5 No Refresh Collision at Variable Latency WRITE (1LC) / Data Input Masking



Notes:

1. The Latency count is defined by the initial latency value in a configuration register.
2. Latency count (LC) is 4 clocks.
3. Diagram in the figure above is representative of **variable latency with no refresh collision access.**
4. Write access (LC) starts once RA [3:0] is captured.
5. The memory drives DQSM "Low" during command address cycles and DQSM goes to "Hi-Z" after command address cycles.
6. The system memory controller must drive DQSM to a valid Low before the end of initial latency (tDMV) to provide a data mask preamble time. This can be done during the last cycle of LC cycle.
7. During Write data input, data is center aligned with the clock.
8. During Write data input, DQSM indicates whether each data byte is masked with DQSM High or not masked with DQSM Low.
9. Data inputs [7:4] of second byte are masked.

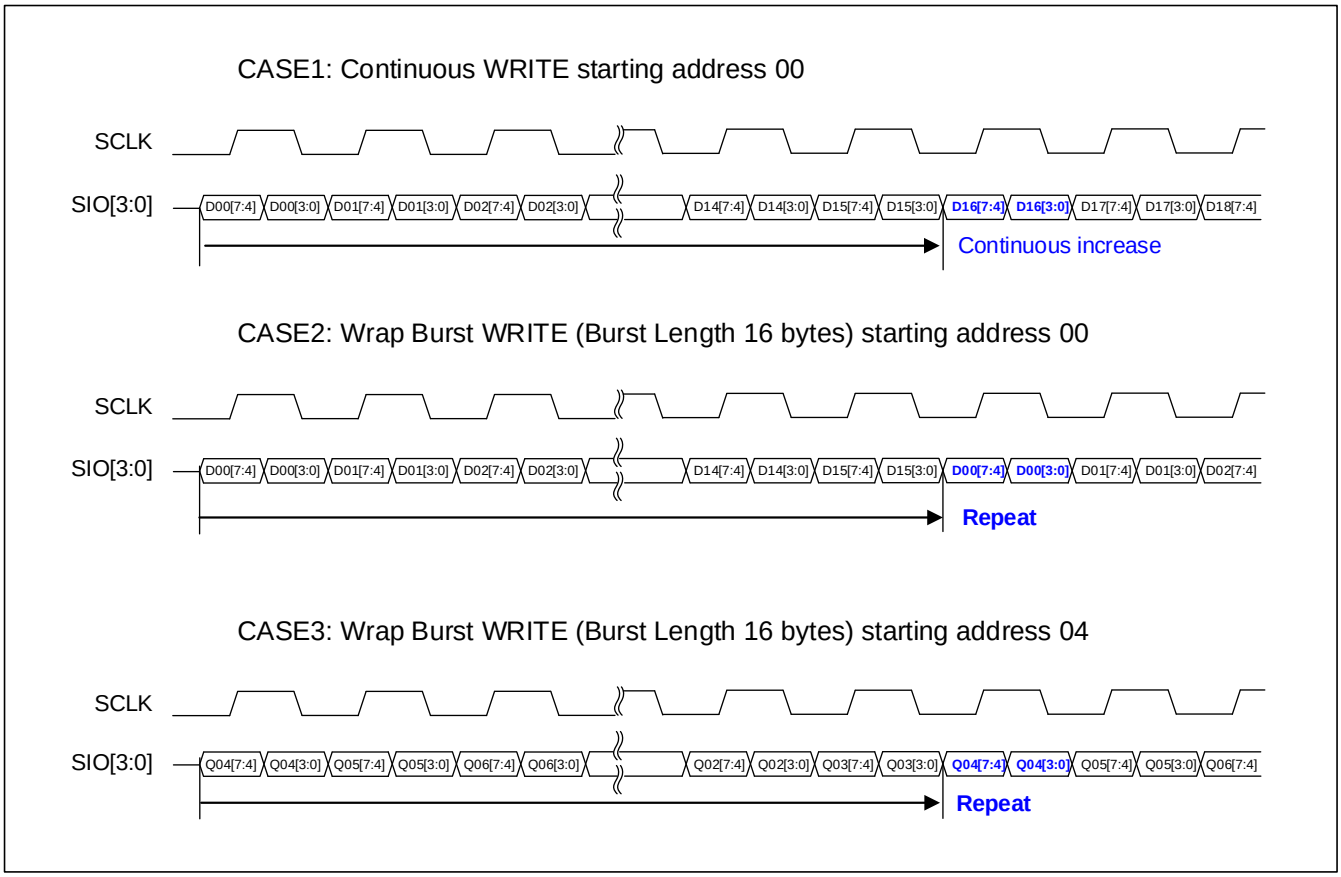
Figure 5.6 Refresh Collision at Variable Latency WRITE (2LC) / Data Input Masking



Notes:

1. The Latency count is defined by the initial latency value in a configuration register.
2. Latency count (LC) is 3 clocks.
3. Diagram in the figure above is representative of **variable latency with refresh collision or fixed-latency access. (2LC operation)**
4. **In this Write there is a latency count (2LC) for WRITE operation**
5. Write access (LC) starts once RA [3:0] is captured.
6. The memory drives DQSM High during command address cycles and DQSM goes to “Hi-Z” after command address cycles.
7. The system memory controller must drive DQSM to a valid Low before the end of initial latency (tDMV) to provide a data mask preamble time.This can be done during the last cycle of LC cycle.
8. During Write data input, data is center aligned with the clock.
9. During Write data input, DQSM indicates whether each half byte (4-bit) is masked with DQSM High or not masked with DQSM Low.
10. Data inputs [7:4] of second byte are masked.

Figure 5.7 WRITE Burst Wrap



Notes:

1. CS# can stay Low between burst operations, but CS# must not remain Low longer than tCSM.
2. Write operation can be ended at any time by bringing CS# High.
3. When continuous burst write reaches the last address in the memory array, continuing the burst will write to the beginning of the address.

5.3 PREAMBLE BIT DATA PATTERN READ OPERATION

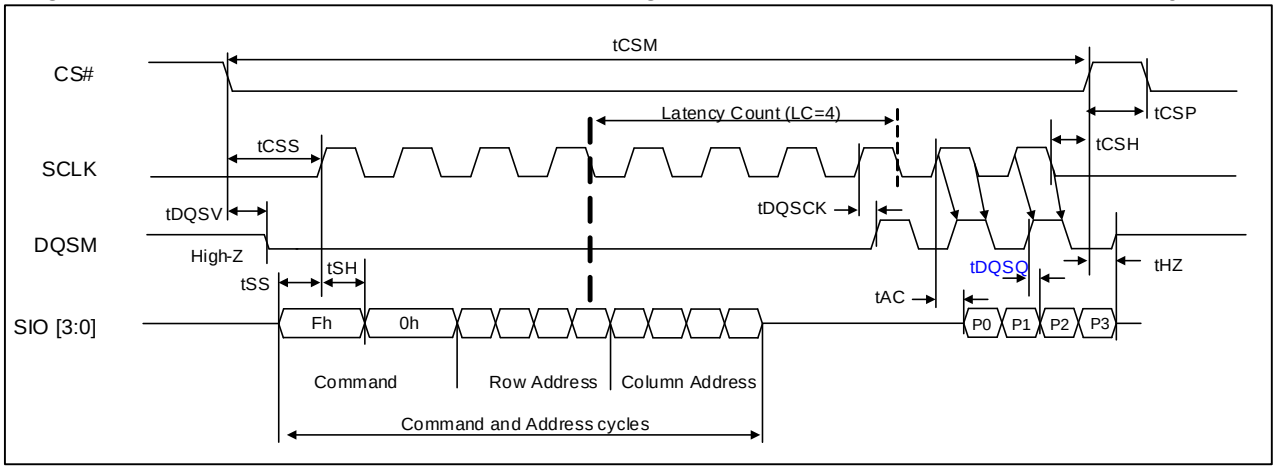
The Preamble Bit Data Pattern READ Operation can improve data capture reliability while the QUADRAM is running in high frequency, while supporting the System/Memory Controller to determine the data output valid windows more easily.

The Preamble Bit is designed as a 16-bits data pattern, it can be output by Preamble Bit READ Command (F0h + 00h). The Row Address and Column Address are “don’t care”, except Column Address CA0 is used for selecting the pattern.

After Preamble Bit READ Command (F0h).and addresses cycles, a fixed 16-bits data pattern will output after initial latency cycles on all 4-SIO pins, according to A0 setting in Column Address. Refer to *"Table 5.1. Preamble Bit Data Pattern SIO assignments"*.

The Latency Count values are defined in configuration register CR [7-4] which is the same as Read timing diagram.

Figure 5.8 Preamble Bit Data Pattern READ Timing, No Refresh Collision at Variable Latency



Notes:

1. Latency Count (LC) = 4 clocks, CR[8]=1 (DQSM 1 clock pre-cycle before Valid READ Data)
2. The memory drives DQSM during the entire Data Learning Pattern Read.
3. The required latency count is device and clock frequency dependent.
4. Column address A0 is used for pattern selection, and Row address RA [12:0] and Column address CA [6:1] are don’t care.

Table 5.1 Preamble Bit Data Pattern SIO assignments

Column Address A0	All SIOs (except SIO3)	SIO3
A0=0	0011 0100 1001 1010	0011 0101 0001 0100
A0=1	0101 0101 0101 0101	0101 0101 0101 0101

5.4 RESET OPERATION

Figure 5.9 RESET Timing

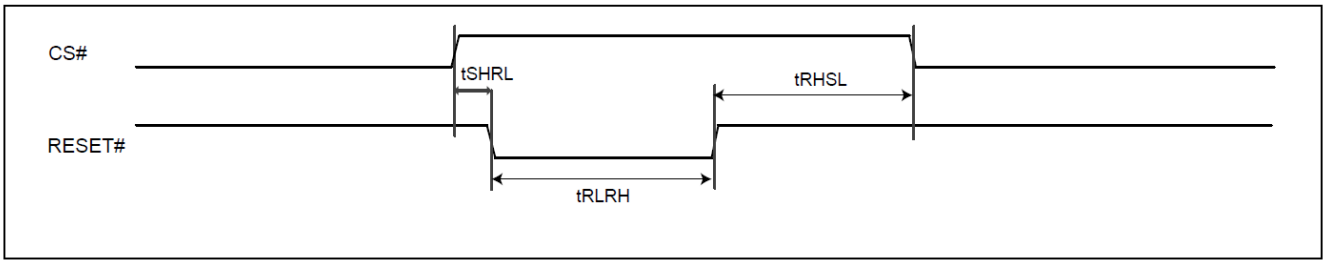
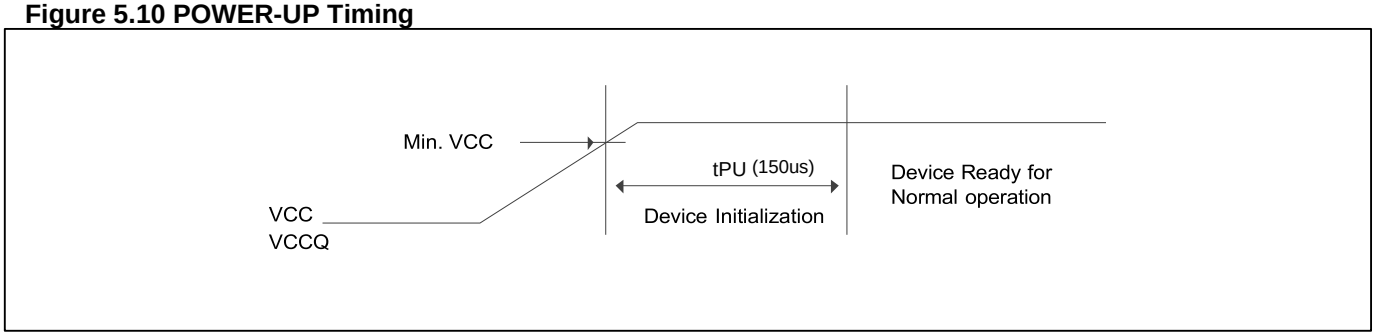


Table 5.2 RESET Timing Parameters

Parameter	Description	Min	Max	Unit
tSHRL	RESET# Low after CS# High	15	-	ns
tRLRH	RESET# Low Pulse width	10	-	us
tRHSL	RESET# High before CS# Low	10	-	us

5.5 POWER-UP INITIALIZATION

Figure 5.10 POWER-UP Timing

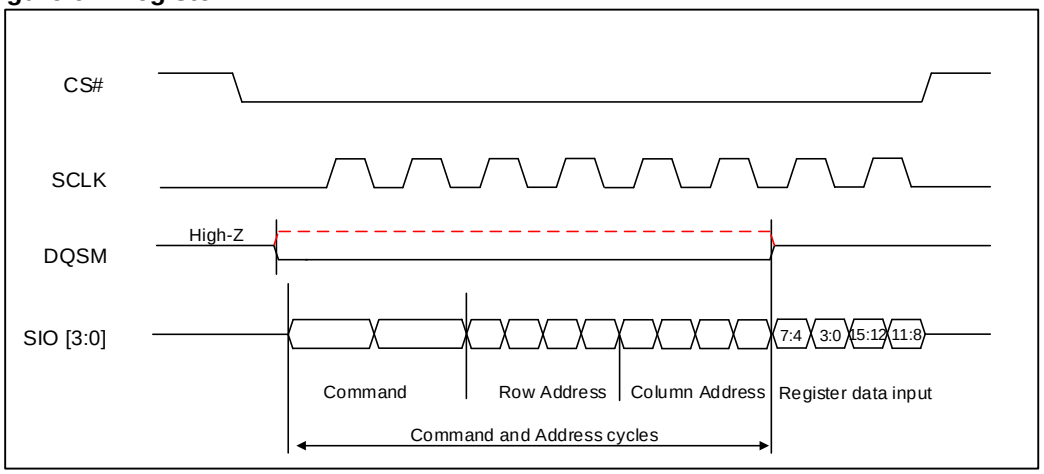


6. REGISTER

The device has 16 bit Configuration Register and ID Register, and they can be accessed by Register Read or Write command.

6.1 REGISTER READ/WRITE OPERATION

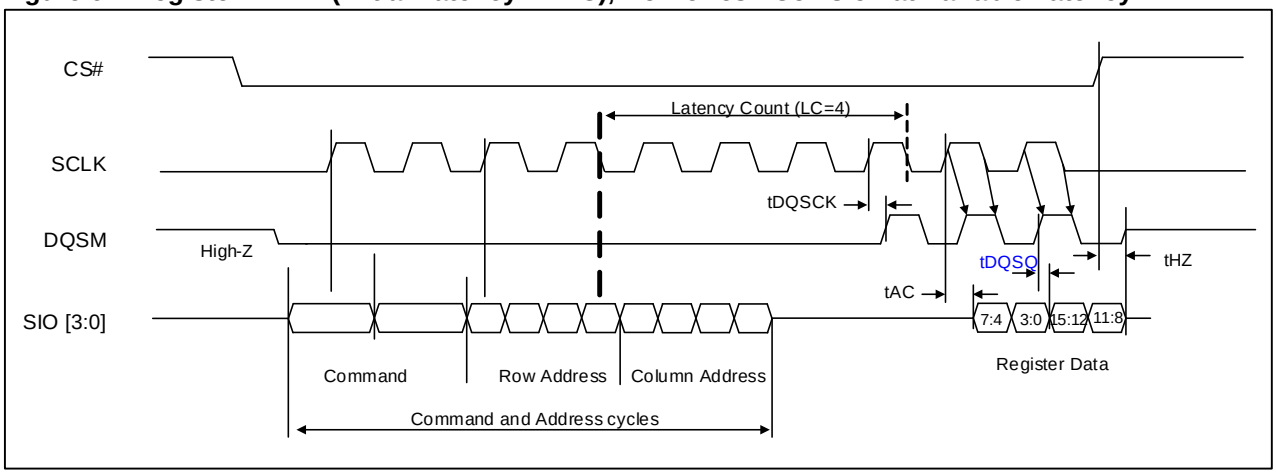
Figure 6.1 Register WRITE



Notes:

1. The device drives DQSM "Low or High for Refresh indication" during command address cycles, which must be ignored by host. DQSM goes to "Hi-Z" after command address cycles.
2. The register value is always provided immediately after the Command Address cycles (0 cycle latency)
3. The DQSM signal keep Hi-Z during register data-input cycles. DQSM will be ignored by host during entire register write operation.
4. **Least Significant Byte first ([7:0]), and Most Significant Byte ([15:8]) later.**

Figure 6.2 Register READ (Initial Latency = 1LC), No Refresh Collision at Variable Latency



Notes:

1. The Latency count is defined by the initial latency value in a configuration register.
2. Latency count (LC) is 4 clocks, CR [8] =1 (DQSM 1 clock pre-cycle before Valid READ Data).
3. Diagram in the figure above is representative of **variable latency with no refresh collision access.**
4. Read access (LC) starts once RA [3:0] is captured (falling edge of 4th Row address clock)
5. The memory drives DQSM during read cycles.
6. DQSM is a read data strobe with data values edge aligned with the transitions of DQSM driven by the device.

6.2 CONFIGURATION REGISTER

The Configuration Register is able to change the defaulted status of the device. The device will be configured after the CR bit is set.

Table 6.1 Configuration Register

	Bit	Function	Settings (Binary)
Most Significant Byte	15	Deep Power Down Enable	1- Normal operation (default) 0- Writing 0 to CR [15] causes the device to enter Deep Power Down.
	14-12	ODS (Output Drive Strength)	Refer to *"Table 6.2. Output Driver Strength Table"*
	11-9	Reserved	Set to 000b
	8	**DQSM READ Pre-cycle**	**1 - 1 clock** **0 - 0 clock (default)**
Least Significant Byte	7-4	Latency counter	Refer to *"Table 6.3. Latency counter Table"*
	3	Initial Access Latency	**0 - Variable Latency (default)** 1 - Fixed Latency
	2	Reserved	Set to 0b
	1-0	Burst Length	00- 128 bytes 01- 64 bytes **10- 32 bytes (default)** 11- 16 bytes

Table 6.2 Output Driver Strength Table

CR[14]	CR[13]	CR[12]	Description
0	0	0	146 Ohms
0	0	1	76 Ohms
0	1	0	52 Ohms
0	1	1	41 Ohms
1	0	0	34 Ohms
1	0	1	30 Ohms
1	1	0	26 Ohms
1	**1**	**1**	**24 Ohms (Default)**

Table 6.3 Latency counter Table

CR[7:4]	Latency Counter
0000	3 clocks
0001	4 clocks
0010	**5 clocks(default at 3V)**
0011	6 clocks
0100	7 clocks
0101	8 clocks**(default at 1.8V)**
0110~1111	Reserved

6.2.1 WRAPPED BURST LENGTH

Table 6.4 Wrapped Burst Sequences

Command	Configuration Register[1:0]	Burst Type	Wrap Boundary Col. Addr	Start address (Hex)	Address Sequence (Hex):Bytes
Read	00	Wrap 128	CA[6:0]	XXXXXX06	06, 07, 08, 09, …. **7E, 7F**, 00, 01, 02, 03, 04, 05, 06, 07, ….
Write	00	Wrap 128	CA[6:0]	XXXXXX06	06, 07, 08, 09, …. **7E, 7F**, 00, 01, 02, 03, 04, 05, 06, 07, ….
Read	01	Wrap 64	CA[5:0]	XXXXXX02	02, 03, 04, 05, …. **3E, 3F**, 00, 01, 02, 03, 04, 05, 06, 07, ….
Write	01	Wrap 64	CA[5:0]	XXXXXX02	02, 03, 04, 05, …. **3E, 3F**, 00, 01, 02, 03, 04, 05, 06, 07, ….
Read	10	Wrap 32	CA[4:0]	XXXXXX1A	1A, 1B, 1C, 1D, **1E, 1F**, 00, 01, …. 0E, 0F, 10, 11, 12, ….
Write	10	Wrap 32	CA[4:0]	XXXXXX1A	1A, 1B, 1C, 1D, **1E, 1F**, 00, 01, …. 0E, 0F, 10, 11, 12, ….
Read	11	Wrap 16	CA[3:0]	XXXXXX0A	0A, 0B, 0C, 0D, **0E, 0F**, 00, 01, …. 08, 09, 0A, 0B, 0C, ….
Write	11	Wrap 16	CA[3:0]	XXXXXX0A	0A, 0B, 0C, 0D, **0E, 0F**, 00, 01, …. 08, 09, 0A, 0B, 0C, ….
Read	XX	Continuous	X	XXXXXX0C	0C, 0D, 0E, 0F, 10, 11, 12, 13, 14, 15, 16, 17, ….
Write	XX	Continuous	X	XXXXXX0C	0C, 0D, 0E, 0F, 10, 11, 12, 13, 14, 15, 16, 17, ….

Notes: When Continuous burst type is operated on burst operations, Memory access address will increase continuously regardless of Burst Wrap Length code.

6.2.2 INITIAL LATENCY (CR [3])

Initial Latency for Variable Latency setting (CR [3]=0) is LC or 2LC , based on Refresh Collision like below table. So host chipset must monitor DQSM signal, which indicates Refresh Collision occurrence or not.
But Initial Latency for Fixed Latency setting (CR [3] = 1) is always 2LC.

Table 6.5 Variable Latency (CR[3] = 0)

Latency code CR[7:4]	Initial Latency Counter		Maximum Operating Frequency (MHz)			
	No Refresh Collision (LC)	Refresh Collision (2LC)	1.8V		3.0V	
			105°C	125°C	105°C	125°C
0000	3 clocks	6 clocks	83		83	
0001	4 clocks	8 clocks	100		100	
0010	**5 clocks (default at 3V)**	**10 clocks**	166	133	**133**	**133**
0011	6 clocks	12 clocks	166	133	166	133
0100	7 clocks	14 clocks	NA			
0101	**8 clocks(default at 1.8V)**	**16 clocks**	**200**	**166**	166	166
0100 - 1111	Reserved	-	NA			

Notes: Default setting for 1.8V device is “0101”, and that for 3.0V device is “0010”.

Table 6.6 Initial Latency Summary Table(1)

Destination	Operating mode	Variable mode (default) initial Latency Count		Fixed mode Initial Latency Count
		No Refresh Collision	Refresh Collision	
Memory	READ	1LC	2LC	2LC
	WRITE	1LC	**2LC(2)**	**2LC(2)**
Register	READ	1LC	**2LC(2)**	**2LC(2)**
	WRITE	0LC		0LC

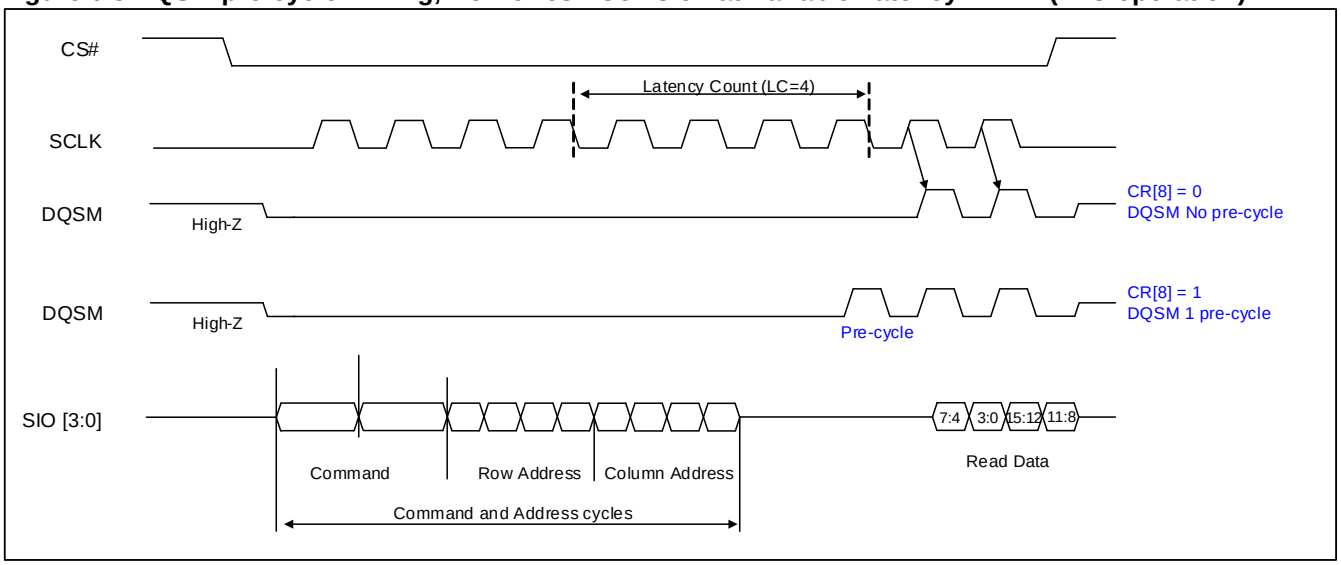
Notes:

1. LC means Latency Counter clocks, which is in Configuration Register Bit [7:4], as defined in *"Table 6.1" and ."Table 6.3"*.
2. Contact ISSI MKT if 1LC is required instead of 2LC.

6.2.3 DQSM READ Pre-Cycle (CR [8])

CR [8] defines DQSM Pre-Cycle.

Figure 6.3 DQSM pre-cycle Timing, No Refresh Collision at Variable Latency READ (1LC operation)



Notes:

1. Latency count (LC) is 4 clocks.
2. When Configuration Register bit [8] = 0, the Device will output DQSM with valid data cycle.
3. When Configuration Register bit [8] = 1, the Device will output 1 pre-cycle (dummy DQSM) prior to valid data cycle.
4. The memory drives DQSM during read cycles.

6.2.4 Deep Power Down (CR [15])

Figure 6.4 Deep Power Down Entry Timing

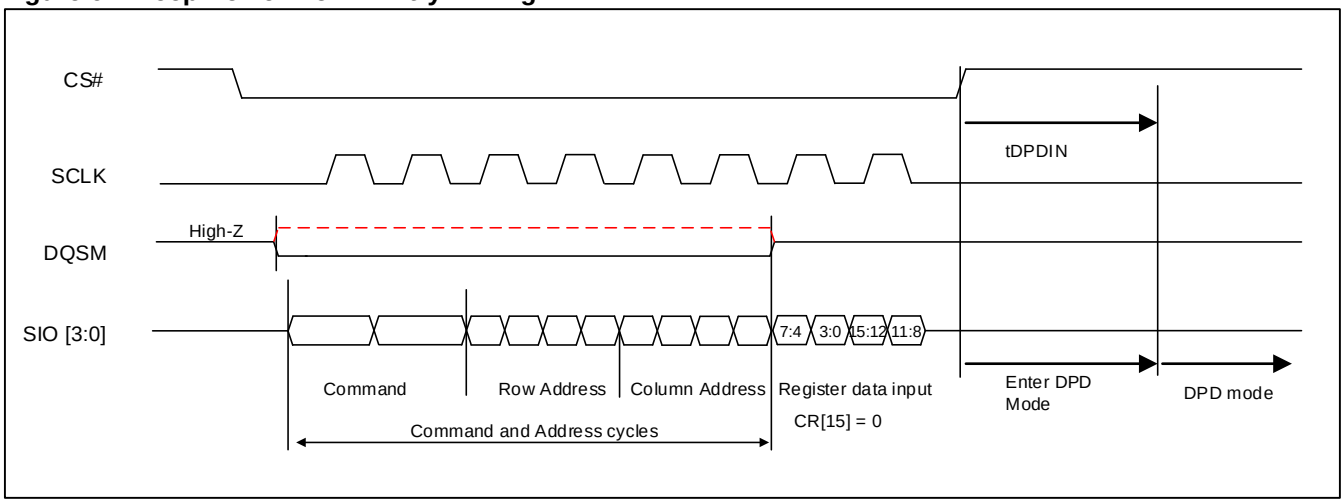
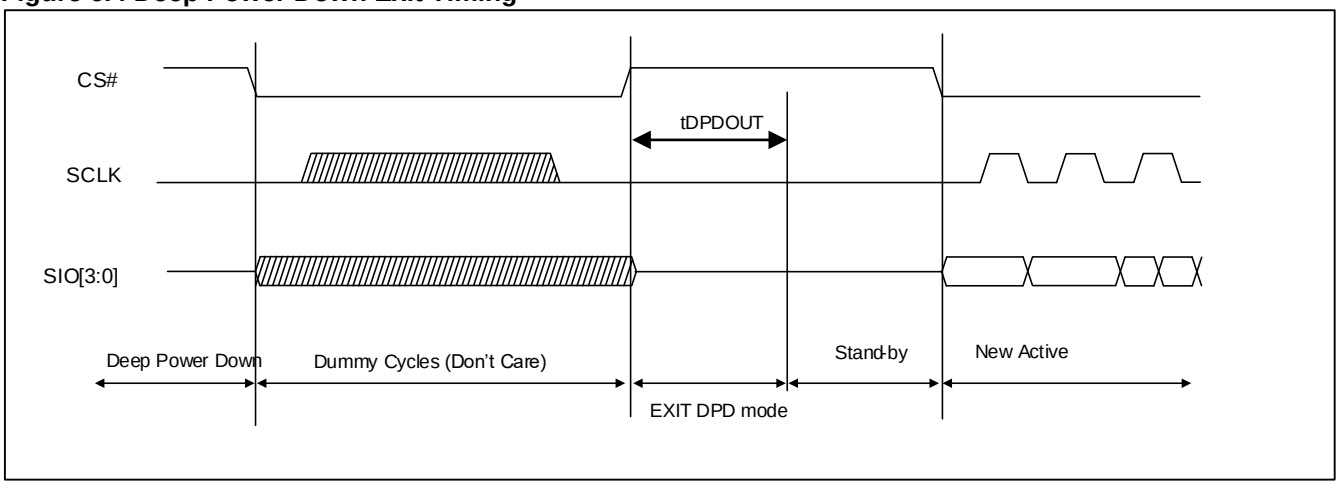


Figure 6.4 Deep Power Down Exit Timing



Note: Memory Cell Data cannot be retained at deep power down(DPD) mode.

Table 6.7 Deep Power Down Timing Parameters

Parameter	Description	Min	Max	Unit
tDPDIN	Deep Power Down CR[15]=0 register write to DPD power level	150	-	us
tDPDX	CS# Low period to exit from Deep Power Down	200	-	ns
tDPDOUT	CS# Low then High to Standby wakeup time	-	150	us

6.3 DEVICE IDENTIFICATION REGISTER

It is a read only, non-volatile, word register that provides device information. The device information fields can be identified as below.

a. Device Type
b. Density
    i. Row address bit count
    ii. Column address bit count
c. Manufacturer

Table 6.8 ID Register

Bits	Function	Settings (Binary)
15 - 13	Device Voltage	000: 1.8V 001: 3V
12 - 8	Row address bit count	00000 : 1 row address ……. 01100 : 13 row address …….. 11111 : 32 row address
7 - 4	Column address bit count	0000 : 1 column address ….. 0110: 7 column address ….. 1111 : 16 column address
3 - 0	Manufacturer	0011 (ISSI)

6.4 IN BAND RESET

The device offers an additional feature of In-Band RESET function, which uses existing SPI signals to initiate a hardware reset, which is different from existing software reset/hardware reset (dedicated RESET# pin);

- Existing software reset commands often depend on the Flash being in a particular mode before they are effective. This makes software based reset sequences depend on slave device and mode.
- Dedicated RESET# pin requires additional pin over traditional 8-pins of SPI device. Also it requires 1 more signal for reset operation.

In Band-RESET operation requires 2-signal pins; CE# and SIO0.

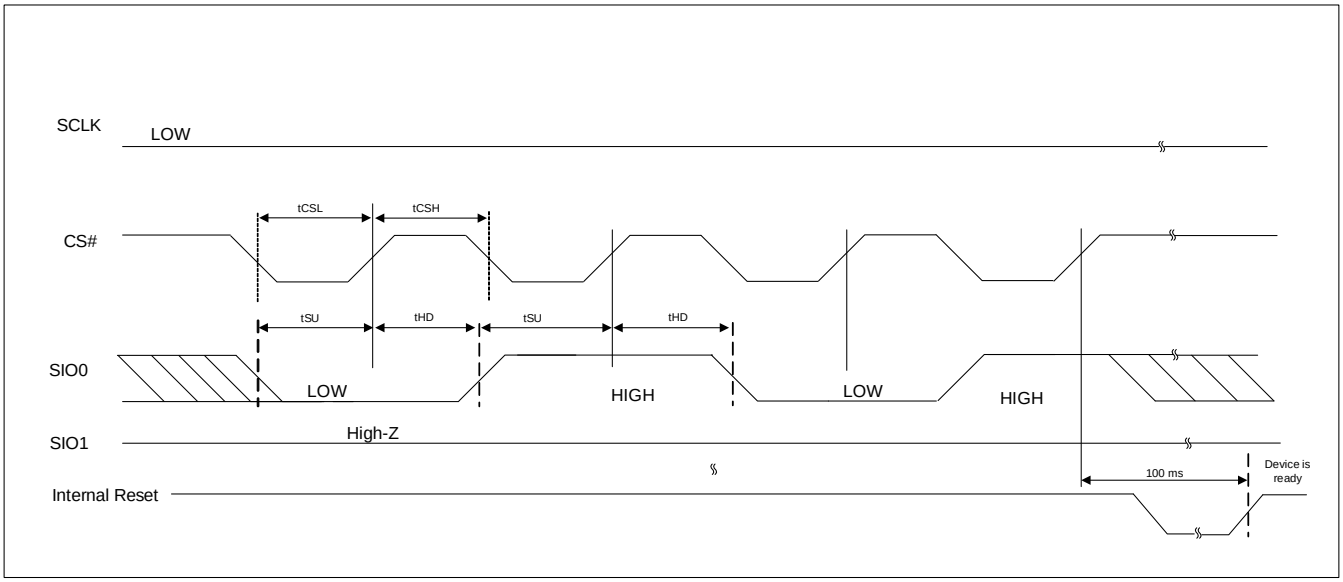
- CS# is driven active low to select the SPI slave (note1)
- Clock (SCLK) remains stable in either a high or low state ….(note 2)
- SIO0 is driven low by the bus master, simultaneously with CS# going active low……(note 3)
- CS# is driven inactive … (note 4)
- Repeat the above 4 steps, each time alternating the state of SIO0.
- After the fourth CS# pulse, the slave triggers its internal reset……..(note 5)

Note 1 This powers up the SPI slave
Note 2 This prevents any confusion with a command, as no command bits are transferred (clocked)
Note 3 No SPI bus slave drives SIO0 during CS# low before a transition of clock. Slave streaming output active is not allowed until after the first edge of clock.
Note 4 The slave captures the state of SIO0 on the rising edge of CS#
Note 5 SIO0 is low on the first CS#, high on the second, low on the third, high on the fourth … (This provides a 5th, unlike random noise)

NOTE:

This reset sequence is not intended to be used at normal power on, but to be used only when the device is not responding to the system. This reset sequence will be operational from any state that the device may be in. During the reset process, the device will ignore any chip select (command).

Figure 6.5 Timing for In-Band RESET Operation



Parameter	Symbol	Min	Max	Units
CS# Low Pulse	tCSL	500	--	ns
CS# High Pulse	tCSH	500	--	ns
Setup Time	tSU	5	--	ns
Hold Time	tHD	5	--	ns

7. ELECTRICAL CHARACTERISTICS

7.1 ABSOLUTE MAXIMUM RATINGS (1)

Storage Temperature	-65°C to +150°C
Input Voltage with Respect to Ground on All Pins	-0.5V to V_{CC} + 0.5V
All Output Voltage with Respect to Ground	-0.5V to V_{CC} + 0.5V
V_{CC}	-0.5V to +2.5V
Electrostatic Discharge Voltage (Human Body Model)(2)	-2000V to +2000V

Notes:

1. **Applied conditions greater than those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.**
2. **ANSI/ESDA/JEDEC JS-001**

7.2 OPERATING RANGE

Operating Temperature	Industrial Grade	-40°C to 85°C
	Automotive Grade A2	-40°C to 105°C
	Automotive Grade A3	-40°C to 125°C
V_{CC} Power Supply	IS66/67WVQ4M4DALL	1.70V (VMIN) –1.95V (VMAX); 1.8V (Typ)
	IS66/67WVQ4M4DBLL	2.7V (VMIN) –3.6V (VMAX); 3.0V (Typ)

7.3 DC CHARACTERISTICS

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_{LI}	Input Leakage Current 3V Device Reset Signal Only	-	-	±10.0	uA	VIN = VSS to VCC, VCC = VCC max
I_{LI}	Input Leakage Current 1.8V Device Reset Signal Only	-	-	±5.0	uA	VIN = VSS to VCC, VCC = VCC max
I_{CC1}	VCC Active Read Current	-	-	20	mA	CS# = VIL, @200MHz, VCC = 1.9V
			-	18		CS# = VIL, @166MHz, VCC = 1.9V
			-	15		CS# = VIL, @133MHz, VCC = 3.6V
I_{CC2}	VCC Active Write Current	-	-	20	mA	CS# = VIL, @200MHz, VCC = 1.9V
			-	18		CS# = VIL, @166MHz, VCC = 1.9V
			-	15		CS# = VIL, @133MHz, VCC = 3.6V
I_{CC4I}	VCC Standby Current at -40°C to +85°C	-	-	200	uA	CS#, VCC=VCC max
I_{CC4IP}	VCC Standby Current at -40°C to +105°C	-	-	300		
I_{CC4IPE}	VCC Standby Current at -40°C to +125°C	-	-	300		
I_{CC5}	Reset Current	-	-	20	mA	CS# = VIH, RESET# = VSS +/- 0.3V, VCC = VCC max
I_{CC6I}	Active Clock Stop Current at -40°C to +85°C	-	-	8	mA	CS# = VIL, RESET# = VCC +/- 0.3V, VCC = VCC max
I_{CC6IP}	Active Clock Stop Current at -40°C to +105°C	-	-	12		
I_{CC7}	VCC Current during power up	-	-	35	mA	CS#,= H, VCC= VCC max, VCC=VCCQ= 1.95V or 3.6V
I_{DPD}	Deep Power Down Current 3V	-	-	30	uA	CS#, VCC = 3.6V, -40°C to +85°C
	Deep Power Down Current 1.8V	-	-	20		CS#, VCC = 1.9V, -40°C to +85°C
I_{DPDP}	Deep Power Down Current 3V	-	-	50	uA	CS#, VCC = 3.6V, -40°C to +105°C
	Deep Power Down Current 1.8V	-	-	30		CS#, VCC = 1.9V, -40°C to +105°C
I_{DPDE}	Deep Power Down Current 3V	-	-	50	uA	CS#, VCC = 3.6V, -40°C to +125°C
	Deep Power Down Current 1.8V	-	-	30		CS#, VCC = 1.9V, -40°C to +125°C
V_{IL}(1)	Input Low Voltage	-0.5		$0.3V_{CC}$	V	
V_{IH}(1)	Input High Voltage	$0.7V_{CC}$		V_{CC} + 0.3	V	
V_{OL}	Output Low Voltage			0.2	V	I_{OL} = 100 µA
V_{OH}	Output High Voltage	V_{CC} - 0.2			V	I_{OH} = -100 µA

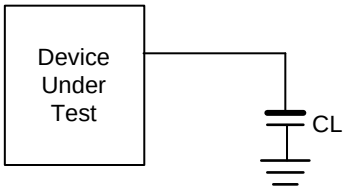
Notes:

1. **Maximum DC voltage on input or I/O pins is VCC + 0.5V. During voltage transitions, input or I/O pins may overshoot VCC by +2.0V for a period of time not to exceed 20ns. Minimum DC voltage on input or I/O pins is -0.5V. During voltage transitions, input or I/O pins may undershoot GND by -2.0V for a period of time not to exceed 20ns.**
2. **Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC} (Typ), TA=25°C.**

AC Measurement Conditions

Symbol	Parameter	Min	Max	Units
CL	Output Load Capacitance		20	pF
TR,TF	Input Rise and Fall Times	2		V/ns
VIN	Input Pulse Voltages	0V to V_{CCQ}		V
VREFI	Input Timing Reference Voltages	VCCQ/2		V
VREFO	Output Timing Reference Voltages	VCCQ/2		V

Figure 7.1 Test Setup



7.4 PIN CAPACITANCE (TA = 25°C, VCC=1.8V/ 3V, 1MHZ)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
C_{IN}	Input Capacitance (CS#, SCLK)	V_{IN} = 0V	3	-	4.5	pF
$C_{IN/OUT}$	Input/Output Capacitance (SIO, DQSM)	$V_{IN/OUT}$ = 0V	3	-	4.0	pF

Note:
1. These parameters are characterized and not 100% tested.

7.5 AC CHARACTERISTICS

7.5.1 Read Timing Parameters (1.8V)

Symbol	Parameter	200MHz		166MHz		Unit
		Min.	Max.	Min.	Max.	
LC	Latency Counter (No Refresh Collision)	8 (1)	-	5 (1)	-	clock
tRWR	Read-Write Recovery Time	40 (1)	-	30 (1)	-	ns
tCK	Clock(CLK) Period	5	-	6	-	ns
tCH	Clock High level width	0.45	-	0.45	-	tCKmi
tCL	Clock Low level width	0.45	-	0.45	-	tCKmi
tHP	Clock half period	Min(tCH,tCL)	-	Min(tCH,tCL)	-	ns
tDQSV	CS# Active to DQSM valid	-	12	-	12	ns
tAC	Clock transition to DQ valid	0.9	5	1	5.5	ns
tDQSCK	Clock transition to DQSM valid	0.9	5	1	5.5	ns
tCSP	CS# High Between READ/WRITE	6	-	6	-	ns
tCSS	CS# Setup to next CLK Rising Edge	3	-	3	-	ns
tCSH	CS# Hold After CLK Falling Edge	2	-	2	-	ns
tIS	Input Setup	0.5	-	0.6	-	ns
tIH	Input Hold	0.5	-	0.6	-	ns
tDQSQ	DQSM-DQ Skew	-	0.4	-	0.45	ns
tQHS	Data Hold Skew factor	-	0.8	-	0.85	ns
tQH	DQ hold time from DQSM	tHP-tQHS	-	tHP-tQHS	-	ns
tLZ	Clock to DQ Low-Z	0	-	0	-	ns
tHZ	CS# Inactive to DQSM and DQ High-Z	-	5	-	6	ns
tCSM	Chip Select Maximum Low Time (~ 85°C)	-	4.0	-	4.0	us
tCSM	Chip Select Maximum Low Time (~ 125°C)	-	1.0	-	1.0	us

Note:

1. Ambient temperature is up to 105°C.

7.5.2 Read Timing Parameters (3.0V)

Symbol	Parameter	166Mhz		133Mhz		Unit
		Min.	Max.	Min.	Max.	
LC	Latency Counter (No Refresh Collision)	6 (1)	-	5 (1)	-	clock
tRWR	Read-Write Recovery Time	36 (1)	-	37.5 (1)	-	ns
tCK	Clock(CLK) Period	6	-	7.5	-	ns
tCH	Clock High level width	0.45	-	0.45	-	tCKmi
tCL	Clock Low level width	0.45	-	0.45	-	tCKmi
tHP	Clock half period	Min(tCH,tCL)	-	Min(tCH,tCL)	-	ns
tDQSV	CS# Active to DQSM valid	-	12	-	12	ns
tAC	Clock transition to DQ valid	1	6.5	2	7	ns
tDQSCK	Clock transition to DQSM valid	1	6.5	2	7	ns
tCSP	CS# High Between READ/WRITE	6	-	7.5	-	ns
tCSS	CS# Setup to next CLK Rising Edge	3	-	3	-	ns
tCSH	CS# Hold After CLK Falling Edge	2	-	2	-	ns
tIS	Input Setup	0.6	-	0.8	-	ns
tIH	Input Hold	0.6	-	0.8	-	ns
tDQSQ	DQSM-DQ Skew	-	0.7	-	0.75	ns
tQHS	Data Hold Skew factor	-	0.85	-	0.90	ns
tQH	DQ hold time from DQSM	tHP-tQHS	-	tHP-tQHS	-	ns
tLZ	Clock to DQ Low-Z	0	-	0	-	ns
tHZ	CS# Inactive to DQSM and DQ High-Z	-	6	-	7	ns
tCSM	Chip Select Maximum Low Time (~ 85°C)	-	4.0	-	4.0	us
tCSM	Chip Select Maximum Low Time (~ 125°C)	-	1.0	-	1.0	us

Note:

1. Ambient temperature is up to 105°C.

7.5.3 WRITE Timing Parameters (1.8V)

Symbol	Parameter	200MHz		166MHz		Unit
		Min.	Max.	Min.	Max.	
LC	Latency Counter (No Refresh Collision)	8 (1)	-	5 (1)	-	clock
tRWR	Read-Write Recovery Time	40 (1)	-	30 (1)	-	ns
tCK	Clock(CLK) Period	5	-	6	-	ns
tCH	Clock High level width	0.45	-	0.45	-	tCKmin
tCL	Clock Low level width	0.45	-	0.45	-	tCKmin
tHP	Clock half period	Min(tCH,tCL)	-	Min(tCH,tCL)	-	ns
tDQSV	CS# Active to DQSM valid	-	12	-	12	ns
tDQSCK	Clock transition to DQSM valid	0.9	5	1	5.5	ns
tCSP	CS# High Between READ/WRITE	6	-	6	-	ns
tCSS	CS# Setup to next CLK Rising Edge	3	-	3	-	ns
tCSH	CS# Hold After CLK Falling Edge	2	-	2	-	ns
tIS	Input Setup	0.5	-	0.6	-	ns
tIH	Input Hold	0.5	-	0.6	-	ns
tDMV	Data Mask Valid (DQSM setup to end of initial latency)	0	-	0	-	ns
tCSM	Chip Select Maximum Low Time (~ 85°C)	-	4.0	-	4.0	us
tCSM	Chip Select Maximum Low Time (~ 125°C)	-	1.0	-	1.0	us

Note:

1. Ambient temperature is up to 105°C.

7.5.4 WRITE Timing Parameters (3.0V)

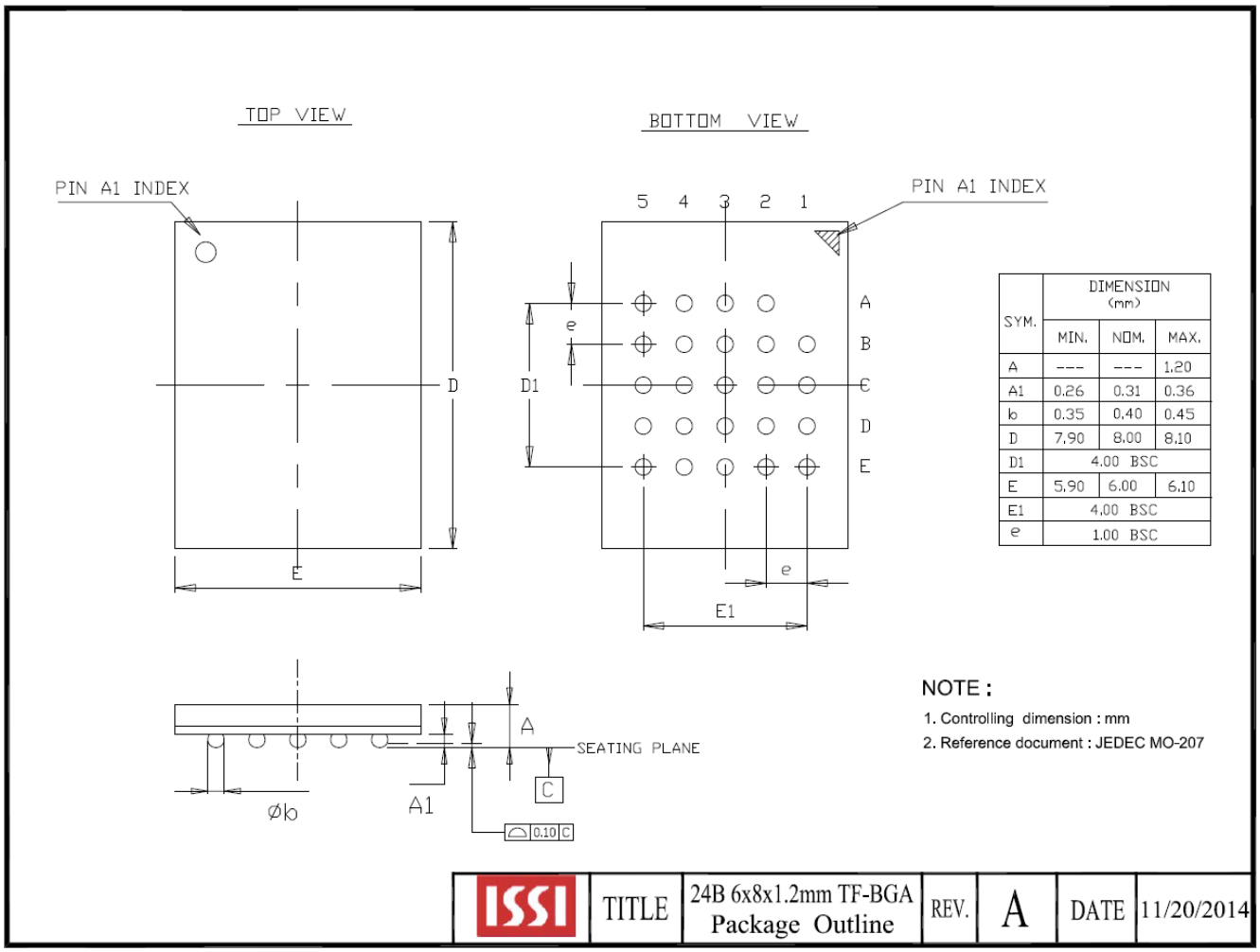
Symbol	Parameter	166MHz		133Mhz		Unit
		Min.	Max.	Min.	Max.	
LC	Latency Counter (No Refresh Collision)	6 (1)	-	5 (1)	-	clock
tRWR	Read-Write Recovery Time	36 (1)	-	37.5 (1)	-	ns
tCK	Clock(CLK) Period	6	-	7.5	-	ns
tCH	Clock High level width	0.45	-	0.45	-	tCKmin
tCL	Clock Low level width	0.45	-	0.45	-	tCKmin
tHP	Clock half period	Min(tCH,tCL)	-	Min(tCH,tCL)	-	ns
tDQSV	CS# Active to DQSM valid	-	12	-	12	ns
tDQSCK	Clock transition to DQSM valid	1	6.5	2	7	ns
tCSP	CS# High Between READ/WRITE	6	-	7.5	-	ns
tCSS	CS# Setup to next CLK Rising Edge	3	-	3	-	ns
tCSH	CS# Hold After CLK Falling Edge	2	-	2	-	ns
tIS	Input Setup	0.6	-	0.8	-	ns
tIH	Input Hold	0.6	-	0.8	-	ns
tDMV	Data Mask Valid (DQSM setup to end of initial latency)	0	-	0	-	ns
tCSM	Chip Select Maximum Low Time (~ 85°C)	-	4.0	-	4.0	us
tCSM	Chip Select Maximum Low Time (~ 125°C)	-	1.0	-	1.0	us

Note:

1. Ambient temperature is up to 105°C.

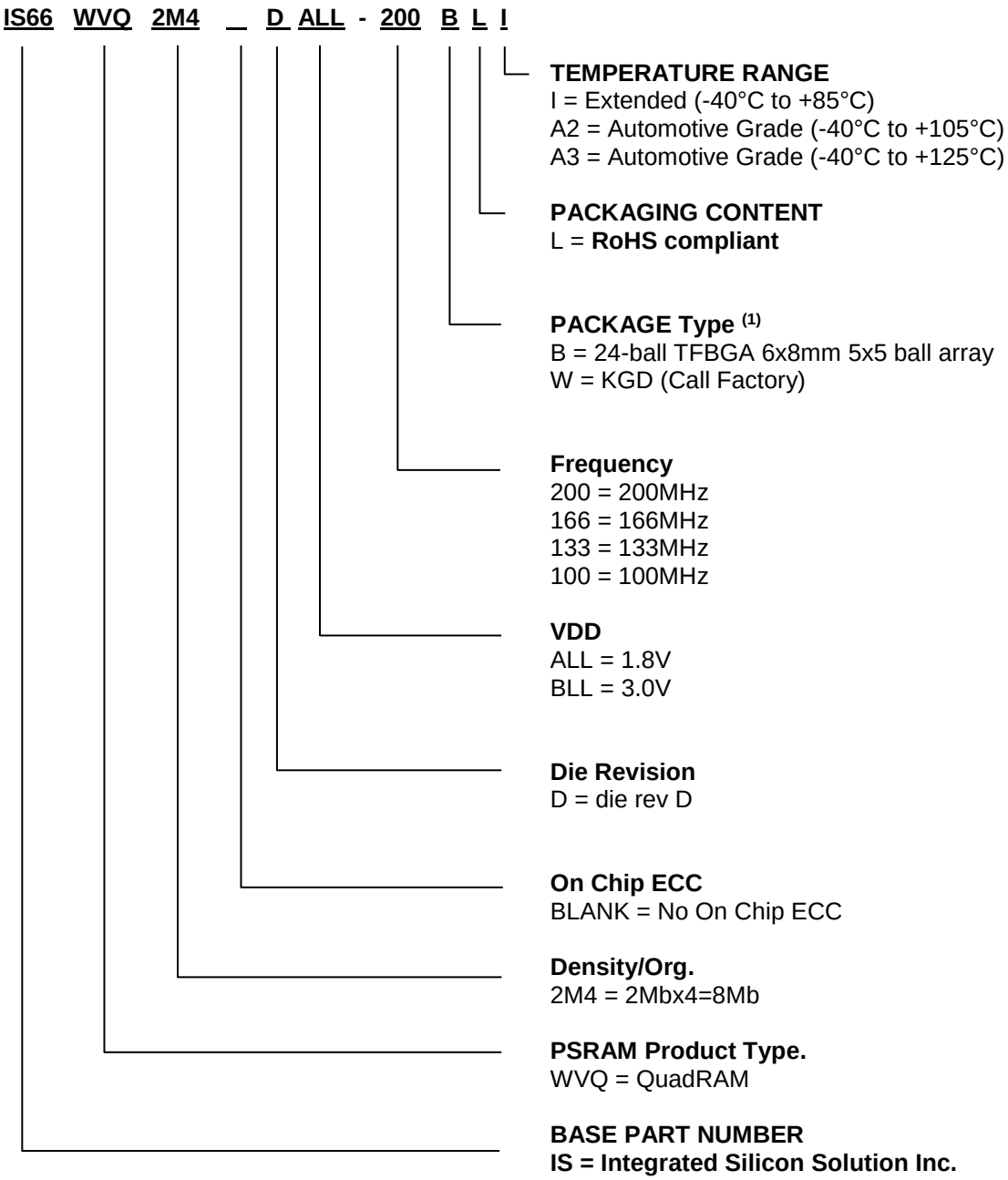
8. PACKAGE TYPE INFORMATION

8.1 24-BALL THIN PROFILE FINE PITCH BGA 6X8MM 5X5 BALL ARRAY (B)



SYM.	DIMENSION (mm)		
	MIN.	NOM.	MAX.
A	---	---	1.20
A1	0.26	0.31	0.36
b	0.35	0.40	0.45
D	7.90	8.00	8.10
D1	4.00 BSC		
E	5.90	6.00	6.10
E1	4.00 BSC		
e	1.00 BSC		

9. ORDERING INFORMATION – Valid Part Numbers



Industrial Temperature Range (-40°C to +85°C)

Config.	Voltage	Package	Frequency (MHz)	Order Part Number
2Mbx4	1.8V	24-ball TFBGA 6x8mm 5x5 ball array	200	IS66WVQ2M4DALL-200BLI
			166	IS66WVQ2M4DALL-166BLI
	3.0V	24-ball TFBGA 6x8mm 5x5 ball array	133	IS66WVQ2M4DBLL-133BLI
			100	IS66WVQ2M4DBLL-100BLI

Automotive A2 Temperature Range (-40°C to +105°C)

Config.	Voltage	Package	Frequency (MHz)	Order Part Number
2Mbx4	1.8V	24-ball TFBGA 6x8mm 5x5 ball array	200	IS67WVQ2M4DALL-200BLA2
			166	IS67WVQ2M4DALL-166BLA2
	3.0V	24-ball TFBGA 6x8mm 5x5 ball array	133	IS67WVQ2M4DBLL-133BLA2
			100	IS67WVQ2M4DBLL-100BLA2

Automotive A3 Temperature Range (-40°C to +125°C)

Config.	Voltage	Package	Frequency (MHz)	Order Part Number
2Mbx4	1.8V	24-ball TFBGA 6x8mm 5x5 ball array	166	IS67WVQ2M4DALL-166BLA3
	3.0V	24-ball TFBGA 6x8mm 5x5 ball array	133	IS67WVQ2M4DBLL-133BLA3
			100	IS67WVQ2M4DBLL-100BLA3